

Supplementary Materials: Tunnel Encapsulation Technology for Durability Improvement in Stretchable Electronics Fabrication

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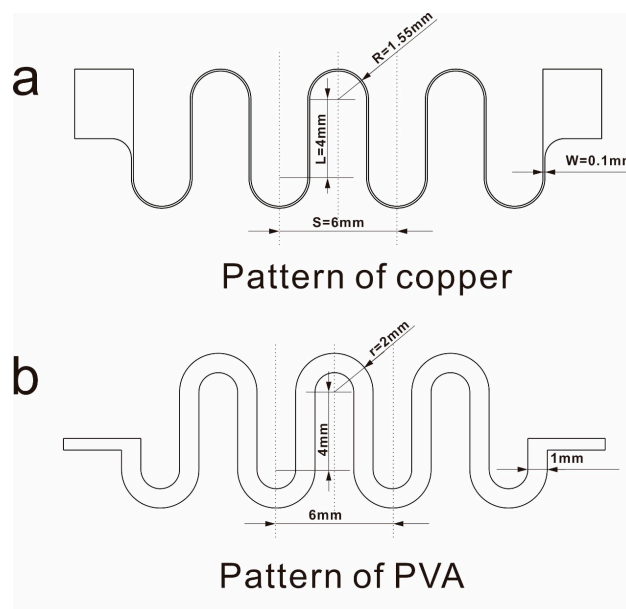


Figure S1. (a) Pattern of copper; (b) Pattern of Polyvinyl Alcohol (PVA).

Finite element analyses (FEA):

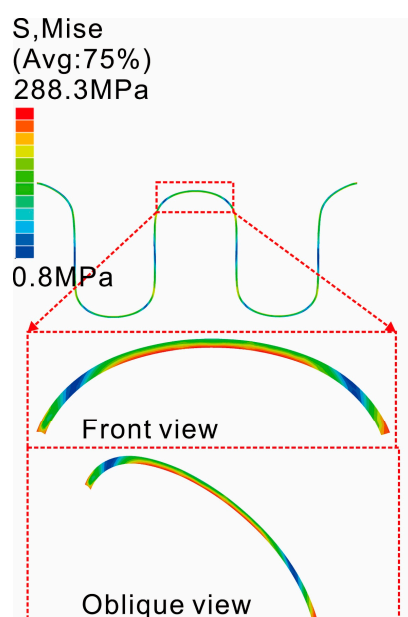


Figure S2. Stress distributions and strain contours of the interconnects with direct encapsulation at 30% elongation.

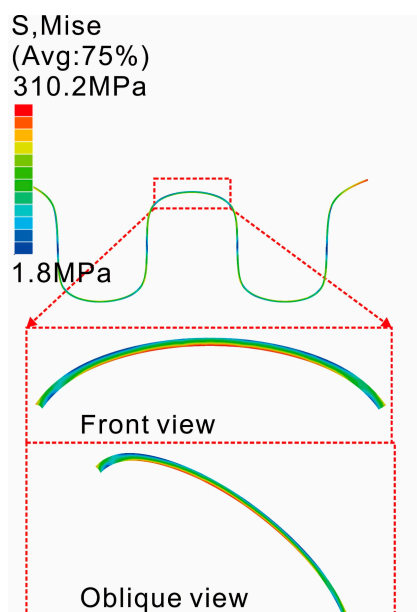


Figure S3. Stress distributions and strain contours of the interconnects with direct encapsulation at 50% elongation.

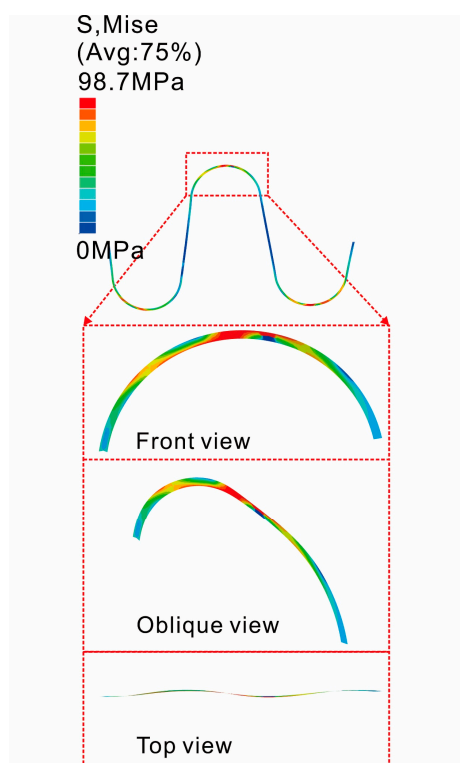


Figure S4. Stress distributions and strain contours of the interconnects with tunnel encapsulation at 30% elongation.

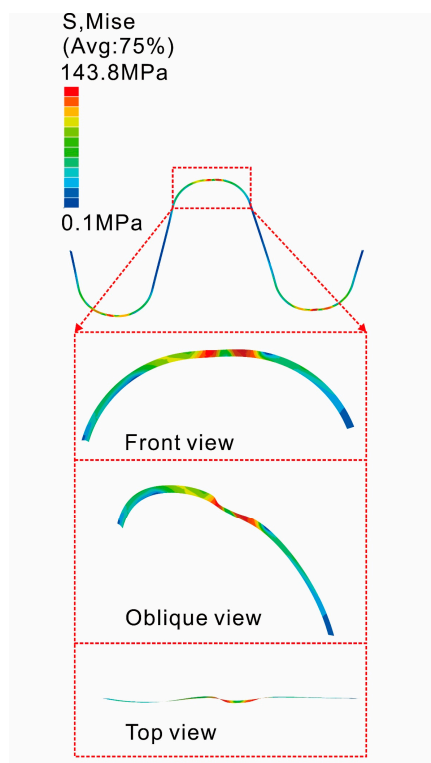


Figure S5. Stress distributions and strain contours of the interconnects with tunnel encapsulation at 50% elongation.

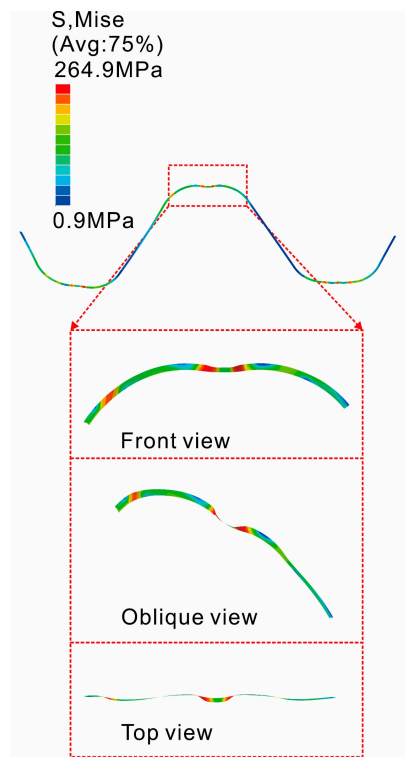


Figure S6. Stress distributions and strain contours of the interconnects with tunnel encapsulation at 100% elongation.

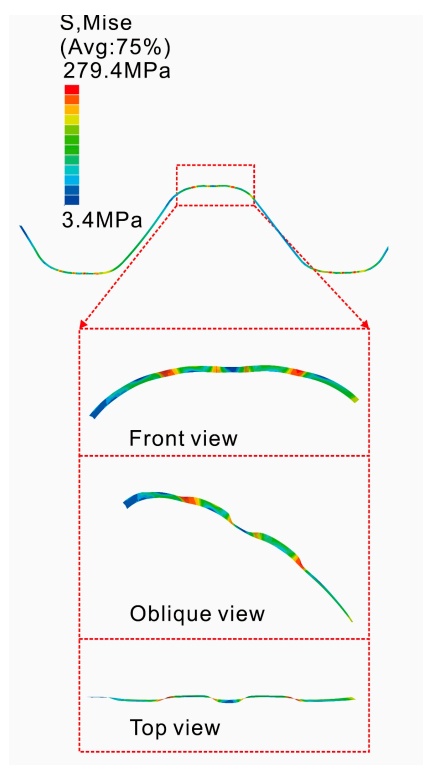


Figure S7. Stress distributions and strain contours of the interconnects with tunnel encapsulation at 110% elongation.